

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC019N04LS	**Issued**	11. April 2021
MA#	MA005345378		
Package	PG-TDSON-8-50	**Weight***	106.41 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.711	0.67	0.67	6684	6684
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		128	
	non noble metal	zinc	7440-66-6	0.055	0.05		512	
	non noble metal	iron	7439-89-6	1.090	1.02		10247	
	non noble metal	copper	7440-50-8	44.271	41.61	42.69	416054	426941
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	395	395
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		800	
	plastics	epoxy resin	-	3.917	3.68		36812	
	inorganic material	silicondioxide	60676-86-0	38.575	36.25	40.01	362518	400130
leadfinish	non noble metal	tin	7440-31-5	1.264	1.19	1.19	11876	11876
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	273	273
solder	noble metal	silver	7440-22-4	0.026	0.02		243	
	non noble metal	tin	7440-31-5	0.052	0.05		486	
	non noble metal	lead	7439-92-1	0.957	0.90	0.97	8992	9721
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	zinc	7440-66-6	0.018	0.02		173	
	non noble metal	iron	7439-89-6	0.368	0.35		3456	
	non noble metal	copper	7440-50-8	14.930	14.03	14.40	140308	143980
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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